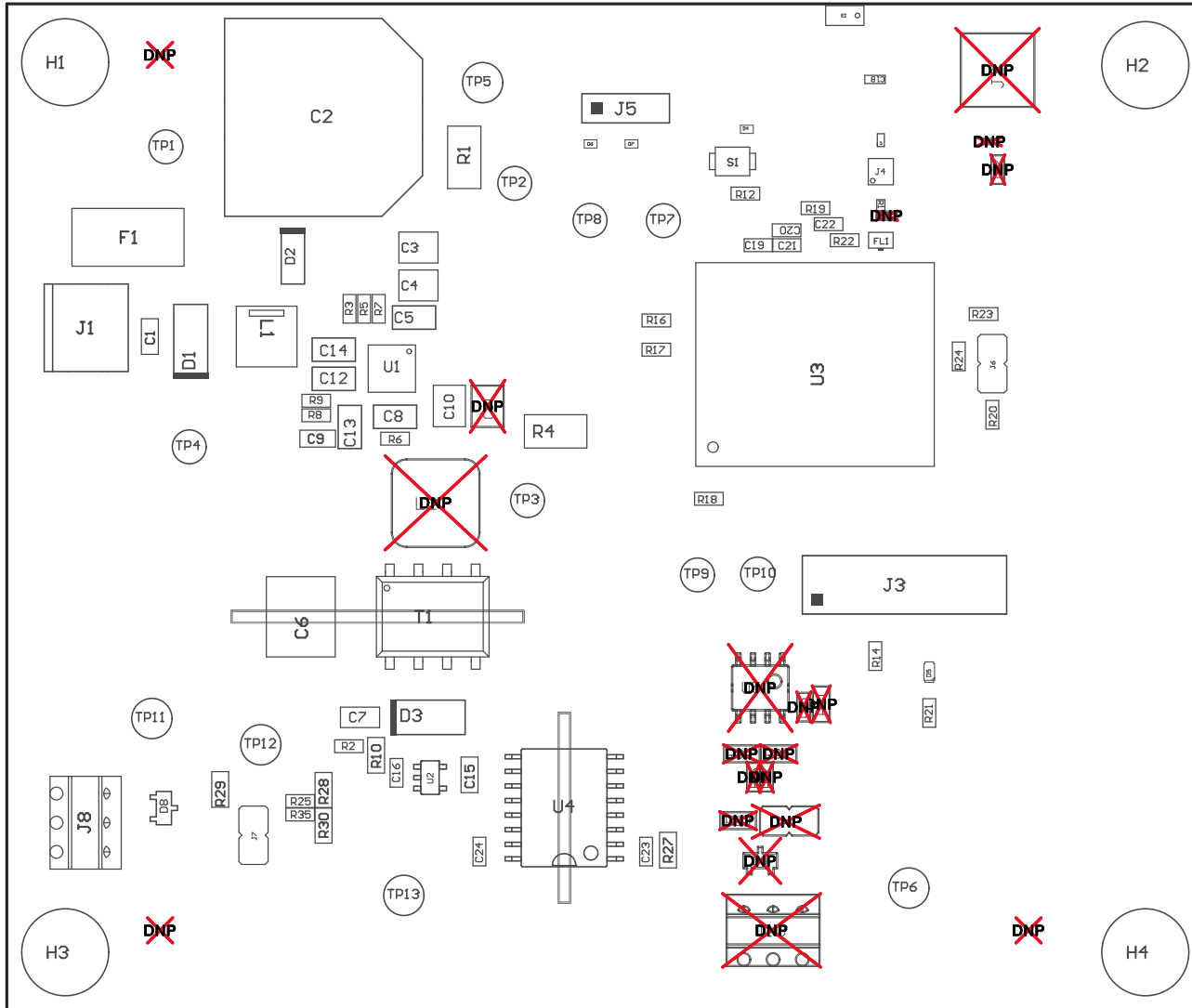
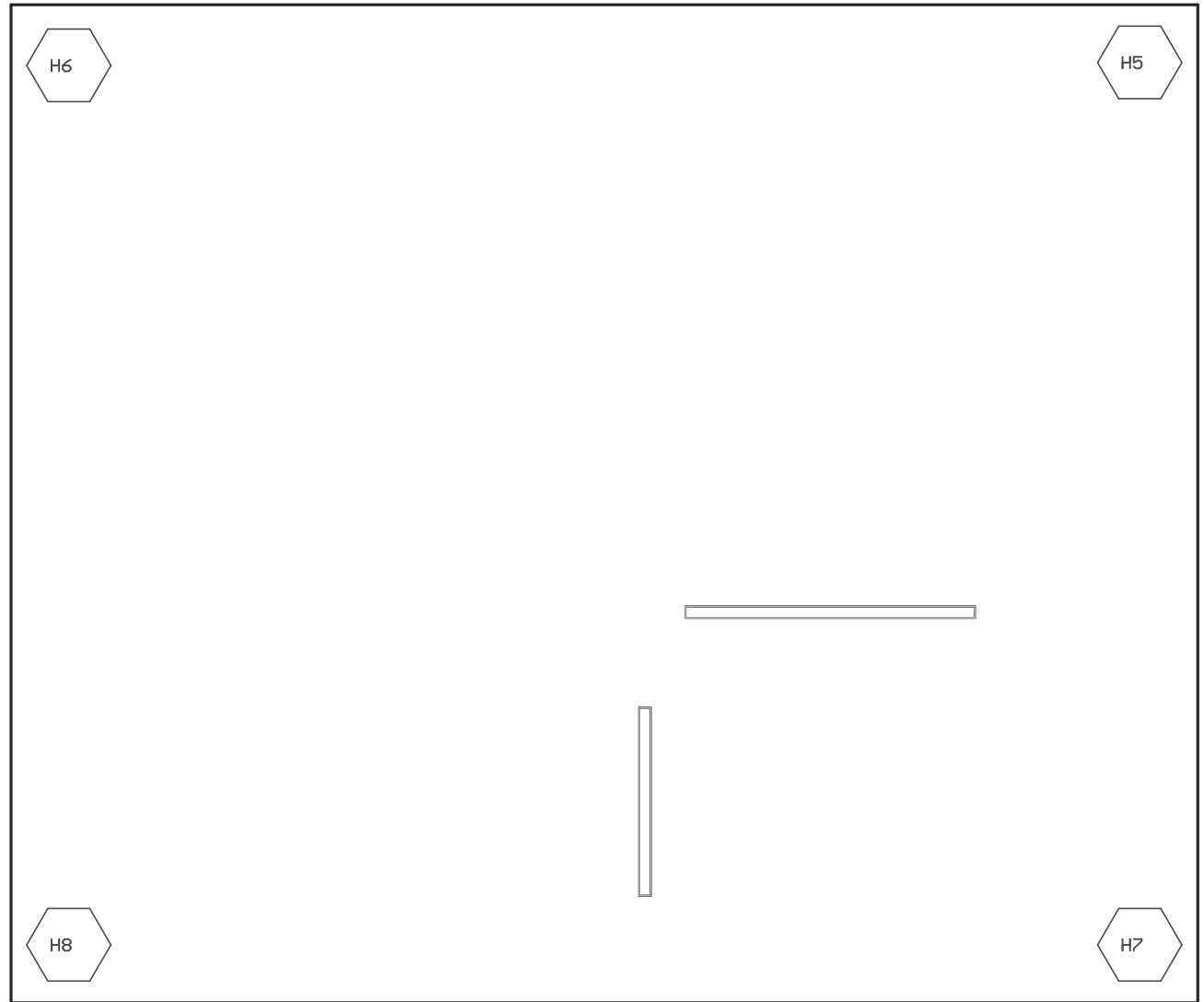


- ZZ1 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ2 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ3 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- ZZ4 ■ Place SH-J6 on J6, SH-J7 on J7, and SH-J9 on J9



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: ISE4033	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-00486		
PLOT NAME = Top Assembly Drawing	GENERATED : 6/15/2015	4:55:22 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: ISE4033	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-00486		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 6/15/2015	4:55:25 PM	TEXAS INSTRUMENTS

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